

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE8457DSJ	**Issued**	3. July 2019
MA#	MA002422482		
Package	PG-DSO-8-44	**Weight***	82.73 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.221	1.48	1.48	14759	14759
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.717	0.87		8669	
	non noble metal	copper	7440-50-8	29.121	35.20	36.12	351995	361205
wire	non noble metal	copper	7440-50-8	0.077	0.09	0.09	930	930
encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1201	
	plastics	epoxy resin	-	4.569	5.52		55225	
	inorganic material	silicondioxide	60676-86-0	44.993	54.39	60.03	543848	600274
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9837	9837
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7860	7860
glue	plastics	acrylic resin	-	0.093	0.11		1130	
	noble metal	silver	7440-22-4	0.331	0.40	0.51	4005	5135
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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